



## Multi Project Wafer Schedule 2019/2020

The timescales indicated below include the preparation of data from the different submissions, fabrication with the maximum amount of process options, and individual dicing. To find out the timescales of standard engineering lots please contact your local sales and support office.

If you cannot find a suitable MPW shuttle in the schedule below, please contact your local sales manager who will check the possibility of additional MPW runs that are available on request.

### X-CMOS 0.13 $\mu\text{m}$ (\*)

PROCESS	TAPE-IN	DATA RELEASE	
XR013	27-May-19	10-Jun-19	
XR013	25-Nov-19	09-Dec-19	
<b>Additional runs available on request.</b>			

### X-CMOS 0.18 $\mu\text{m}$ (\*)

PROCESS	TAPE-IN	DATA RELEASE	
XH018	14-Nov-18	28-Nov-18	
XH018	25-Jan-19	08-Feb-19	
XH018	07-May-19	21-May-19	
XH018	05-Aug-19	19-Aug-19	
XH018	07-Nov-19	14-Nov-19	
<b>Available metal stack options for XH018 MPW runs:</b> 4 Metal Layers: MET1-MET2-MET3-METMID; MIM or MIMH are optional capacitor modules 6 Metal Layers: MET1-MET2-MET3-MET4-METMID-METTHK; MIM or MIMH are optional capacitor modules			

PROCESS	TAPE-IN	DATA RELEASE	
XP018	14-Feb-19	28-Feb-19	
XP018	27-Jun-19	11-Jul-19	
XP018	17-Oct-19	31-Oct-19	
<b>Available metal options for XP018 MPW runs:</b> 4 Metal Layers: MET1-MET2-MET3-METMID; MIM or MIMH are optional capacitor modules 6 Metal Layers: MET1-MET2-MET3-MET4-METMID-METTHK; MIM or MIMH are optional capacitor modules			

PROCESS	TAPE-IN	DATA RELEASE	
XT018	02-Oct-18	16-Oct-18	
XT018	11-Jan-19	25-Jan-19	

PROCESS	TAPE-IN	DATA RELEASE
XT018	29-Mar-19	12-Apr-19
XT018	14-Jun-19	28-Jun-19
XT018	30-Aug-19	13-Sep-19
XT018	15-Nov-19	29-Nov-19

**\*\*THKCOP module is not available for this MPW run.**

Available metal stack options for XT018 MPW runs:  
**4 Metal Layers: MET1-MET2-MET3-METTHK; MIMH as optional capacitor module**  
**6 Metal Layers: MET1-MET2-MET3-MET4-METMID-METTHK; MIM or MIMH are optional capacitor modules**

PROCESS	TAPE-IN	DATA RELEASE
XS018	06-Mar-19	20-Mar-19
XS018	18-Sep-19	02-Oct-19

**\*\*This MPW run covers only a restricted set of modules. Only limited LVT & PPD option will be offered. Please check with your X-FAB contact prior to tape-in.**

Available metal stack options for XS018 MPW runs:  
**4 Metal Layers: MET1-MET2-MET3-MET4-METTHIN; MIM23 or MIMH23 are optional capacitor modules**  
**6 Metal Layers: MET1-MET2-MET3-MET4-MET5-METMID; MIM or MIMH are optional capacitor modules**

### X-CMOS 0.35 μm (\*)

PROCESS	TAPE-IN	DATA RELEASE
XH035	18-Jan-19	01-Feb-19
XH035	10-May-19	24-May-19
XH035	16-Aug-19	30-Aug-19
XH035	15-Nov-19	29-Nov-19


Additional runs available on request.  
Usable modules: MOS, MOSSA, ISOMOS, THKOX, NMVMOS, PMVMOS, HVMOSMID, DEPL, BURDIF, CAPPOLY, HRPOLY, XRPOLY, TEEPROM, MIM, DMIM, METAL2, THKMET3, METAL4, THKMET, OTP, NHVETHK, PHVEMID, PHVETHK, NHVEMID

### X-CMOS 0.6 μm (\*)

PROCESS	TAPE-IN	DATA RELEASE
XC06	29-Mar-19	12-Apr-19
XC06	06-Sep-19	20-Sep-19

### X-DIMOS 1.0 μm (\*)

PROCESS	TAPE-IN	DATA RELEASE
XDH10/XDM10	08-Mar-19	22-Mar-19

 <p>PROCESS</p> <p>XDM10, XDM10</p>	<p>TAPE-IN</p> <p>06-Sep-19</p>	<p>DATA RELEASE</p> <p>20-Sep-19</p>	
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**\* Notes:**

Please make sure to submit your online SIFO, first GDS2 and PO by the Tape-in (Tape-out) deadline.

By the data release date, the **DRC clean and released database** plus all necessary documentation must be submitted in order to participate in the MPW shuttle.

The samples out date is based on the assumption that the most complex process variant is being used. By this date, dice in wafflepack can be delivered.

All changes to above schedule will be automatically updated on this web page only.

**In order to ensure that your device can be included in the MPW run, we encourage you to contact your local sales and support office or you send an email to:**

**[sifo\(at\)xfab.com](mailto:sifo@xfab.com)**